


**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCI No.</b>	AMS/23/14267	
<b>1.3 Title of PCI</b>	Qualification of new substrate with Doosan core material for SUNCHON products family.	
<b>1.4 Product Category</b>	Mems SUNCHON family	
<b>1.5 Issue date</b>	2023-08-23	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	NEMETH KRISZTINA
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<b>2.1.3 Email</b>	krisztina.nemeth@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Andrea Mario ONETTI
<b>2.1.2 Marketing Manager</b>	Simone FERRI
<b>2.1.3 Quality Manager</b>	Michele CALDERONI

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	ST CALAMBA

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Substrate with Mitsubishi core material.	Substrate with Doosan core material.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No Impact. (Specifically for this product, "leadframe" mentioned in paragraph 3.2 has to be intended as LGA substrate)	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Assy throughput enhancement.
<b>5.2 Customer Benefit</b>	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Dedicated FGs
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2023-11-15
<b>7.2 Intended start of delivery</b>	2023-11-15
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>			
<b>8.2 Qualification report and qualification results</b>	In progress	<b>Issue Date</b>	

**9. Attachments (additional documentations)**

14267 Public product.pdf
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10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ISM330ISNTR	
	ISM330ISTR	
	LSM6DSO16ISTR	

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